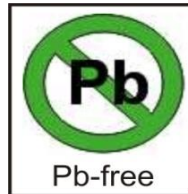
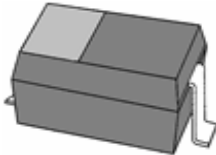




# SEMICONDUCTOR Small Signal Products

## MATERIAL CONTENT LIST

**PACKAGE FAMILY:** **SOD-323**  
**DATE:** July 24, 2020  
**REVISION:** 16



MATERIAL CONTENT					
Part	Material	CAS N°	weight mg	% of weight	ppm of total weight
<b>Mold compound</b> <b>64.5%</b>	Silicon Fused	60676-86-0	2.07	73.9%	476693
	Cured polymer (epoxy + phenolic resin reacted)		0.67	23.9%	154292
	Antimony Trioxide	1309-64-4	0.03	1.1%	6909
	Carbon	7440-44-0	0.03	1.1%	6909
	<b>TOTAL</b>		<b>2.80</b>		
<b>Lead frame</b> <b>29.9%</b>	Si	7440-21-3	0.004	0.3%	875
	Mn	7439-96-5	0.01	0.8%	2303
	Ni	7440-02-0	0.54	41.6%	124355
	Co	7440-48-4	0.007	0.5%	1497
	Fe	7439-89-6	0.74	56.6%	169491
	Cr	7440-47-3	0.0015	0.1%	345
	C	7440-44-0	0.0003	0.0%	69
	Cu	7440-50-8	0.0015	0.1%	345
	<b>TOTAL</b>		<b>1.2996</b>		
<b>L/F plating</b> <b>0.8%</b>	Ag	7440-22-4	0.033	100.0%	7599
	<b>TOTAL</b>		<b>0.03</b>		
<b>Terminal finish</b> <b>2.6%</b>	Sn	7440-31-5	0.114	100.0%	26253
	<b>TOTAL</b>		<b>0.11</b>		
<b>Silicon chip</b> <b>1.7%</b>	Si	7440-21-3	0.074	99.6%	17041
	SiO <sub>2</sub>	14808-60-7	0.0003	0.4%	74
	<b>TOTAL</b>		<b>0.0743</b>		
<b>Chip Metal</b> <b>0.1%</b>	Au	7440-57-5	0.0065	100.0%	1497
	And / or traces of As, Ag, Ti, Al, Ni, Pd, Cu				
	<b>TOTAL</b>		<b>0.01</b>		
<b>Bond wire</b> <b>0.3%</b>	Au	7440-57-5	0.015	100.0%	3454
	<b>TOTAL</b>		<b>0.015</b>		
<b>Total weight</b>			<b>4.3</b>		

Remark: Total weight range  $\pm 10\%$   
 Reflow Soldering acc. J-STD-020  
 Material Analyses Reports available on request